



## Material Content Data Sheet



<b>Sales Product Name</b>		BBY 57-02V H6327		<b>Issued</b>		29. August 2013		
<b>MA#</b>		MA000787826						
<b>Package</b>		PG-SC79-2-1		<b>Weight*</b>		1.68 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	arsenic	7440-38-2	0.000	0.00		18	
	noble metal	gold	7440-57-5	0.003	0.18		1787	
	inorganic material	silicon	7440-21-3	0.026	1.53	1.71	15265	17070
leadframe	inorganic material	silicon	7440-21-3	0.000	0.01		92	
	non noble metal	titanium	7440-32-6	0.001	0.05		460	
	non noble metal	chromium	7440-47-3	0.002	0.14		1379	
	non noble metal	copper	7440-50-8	0.767	45.78	45.98	457955	459886
wire	non noble metal	copper	7440-50-8	0.007	0.39	0.39	3925	3925
encapsulation	organic material	carbon black	1333-86-4	0.007	0.43		4339	
	plastics	epoxy resin	-	0.124	7.38		73755	
	inorganic material	silicondioxide	60676-86-0	0.596	35.58	43.39	355759	433853
leadfinish	non noble metal	tin	7440-31-5	0.055	3.26	3.26	32575	32575
plating	noble metal	silver	7440-22-4	0.088	5.27	5.27	52691	52691
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

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